

ABSTRACT

The present disclosure provides a wafer, a wafer surface nano-topography prediction method, apparatus, device and medium, and relates to the field of semiconductor manufacturing. The method includes: in a process of manufacturing a wafer, performing filtration and data processing on obtained surface topography measurement data of a wafer using a stepwise-designed filter, to obtain a measured nano-topography value nt of the wafer; and predicting a predicted nano-topography value NT of the wafer after a follow-up manufacturing process based on a prediction function $f(nt) = NT$ and the measured nano-topography value nt of the wafer.

(Figure 1)